



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D
<i>* : Required Field</i>			

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2014-02-12
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Giuseppe Vitali Palma	<b>Representative Title</b>	AMS/IPD Materials Declaration Champion)
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDO7*3172AG6	A	BO2A	2014-02-12
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles	 life.augmented	
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.85X3.9X1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	<b>true</b>
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	<b>false</b>
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	<b>false</b>
Product(s) does not meet EU RoHS requirements and is not under exemptions	<b>false</b>
Product(s) is obsolete, no information is available	<b>false</b>
Product(s) is unknown, no information is available	<b>false</b>
Exemption Id.	Description

QueryList : REACH-16th December 2013				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				<b>true</b>
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDO7*3172AG6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	4.14	mg	supplier	die	Silicon (Si)	7440-21-3		4.072	mg	983575	50900
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	1449	75
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.026	mg	6280	325
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.036	mg	8696	450
Leadframe	Copper & its alloys	37.106	mg	supplier	alloy	Copper (Cu)	7440-50-8		37.011	mg	997440	462638
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.017	mg	458	213
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.031	mg	835	388
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1186	550
Leadframe				supplier	metallization	Palladium (Pd)	7440-05-3		0.001	mg	27	13
Leadframe				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	27	13
Leadframe				supplier	metallization	Silver (Ag)	7440-22-4		0.001	mg	27	13
Die attach	Other Organic Materials	1.267	mg	supplier	glue	Silver (Ag)	7440-22-4		1.153	mg	910024	14413
Die attach				supplier	glue	acrylate	Proprietary		0.063	mg	49724	788
Die attach				supplier	glue	Methacrylate	Proprietary		0.051	mg	40253	638
Bonding wire	Other inorganic materials	0.054	mg	supplier	wire	Copper (Cu)	7440-50-8		0.054	mg	1000000	675
encapsulation	Other Organic Materials	37.433	mg	supplier	mold compound	Epoxy Resin	Proprietary		2.807	mg	74987	35088
encapsulation				supplier	mold compound	Phenol Resin	Proprietary		1.872	mg	50009	23400
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		32.417	mg	866001	405213
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.187	mg	4996	2338
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.15	mg	4007	1875